



<b>Form Type</b>	Distribute	<b>Version</b>	2.0	<b>Ref</b>	IPC 1752A	<b>Sectionals</b>	Manufacturing Info/ Material Info	<b>Subsectionals</b>	D, A
<b>Supplier Information</b>									
<b>Company Name</b>	TE Connectivity	<b>Request Document ID</b>		<b>Contact Name</b>	Penica, John R	<b>Contact Title</b>	Mgr Environmental Engineering		
<b>Company Unique ID</b>	-	<b>Response Date</b>	2014-06-23	<b>Contact Email</b>	jrpenica@te.com				
<b>Contact Phone Number</b>		17175923266							
<b>Legal Statement</b>									
<b>Supplier Acceptance</b>	true								
<b>Legal Statement</b>									
The information provided in this document is based upon reasonable inquiry of our suppliers. This information is subject to change. This information does not in any way modify existing purchase specifications or existing contractual or other agreements terms between TE Connectivity (or its affiliated companies) and its customers.									
<b>Product</b>									
<b>Manufacturer Item number</b>	193796-1	<b>Amount</b>	1630.001	<b>Version</b>	-	<b>Identity</b>			
<b>Manufacturer Item Name</b>		<b>Weight Uom</b>	mg	<b>Mfr Site</b>		<b>Authority</b>			
<b>Date</b>		<b>UOM</b>	Each						
<b>EURoHS-0508</b>	Product(s) does not meet EU RoHS requirements and is not under exemptions - true								
<b>ChinaRoHS-0508</b>	Product(s) requires marking for the presence of restricted substances and must be marked with an Environmental Protection Use Period under China's Measures for Administration of the control of pollution by Electronic Information Products - true								
<b>Manufacturing Information</b>									
<b>J-STD-020 MSL Rating</b>		<b>Max Total a Wave Time</b>		<b>Ramp Rate</b>		<b>Wave Additional Info</b>			
<b>Classification Temp</b>		<b>Max Wave Solder Time</b>	0.0	<b>Ramp Down Rate</b>		<b>Psi Rating Reflow</b>			
<b>Max Time Within 5</b>		<b>Psi Rating Wave</b>		<b>Package Designator</b>		<b>Size</b>	0.0		
<b>Time Above 217</b>		<b>Reflow Additional Info</b>		<b>Preheat Max Temp</b>		<b>Terminal Base Alloy</b>	NAC		
<b>Preheat Duration</b>		<b>bulk Solder Termination</b>	NAC	<b>Nbr or Reflow Cycles</b>		<b>Terminal Plating</b>	NAC		
<b>Preheat Min Temp</b>		<b>Nbr of Instances</b>	0	<b>Component Temp Spike</b>		<b>Shape</b>	NAC		
<b>Product Disclosure</b>									
<b>Sub-Item/Material/Substance</b>	<b>Level</b>	<b>Name</b>	<b>Substance Category</b>	<b>Substance CAS</b>	<b>Substance Concentration</b>	<b>Quantity</b>	<b>Mass per Unit</b>	<b>UOM</b>	<b>Exemption</b>
Material	1	Silver Plate				1.0	17.619	mg	
Substance	2	Silver	Supplier	7440-22-4	96.04	1.0	16.92129	mg	
Substance	2	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-1212	1.96	1.0	0.34533	mg	
Substance	2	Chromic acid (H2CrO4), silver(1) salt (1:2)	Chromium VI Compounds	7784-01-2	2.0	1.0	0.35238	mg	
Material	1	Copper				1.0	1609.4	mg	
Substance	2	Manganese	Supplier	7439-96-5	0.02	1.0	0.32188	mg	
Substance	2	Chromium	Supplier	7440-47-3	0.0010	1.0	0.016094	mg	
Substance	2	Antimony	Supplier	7440-36-0	0.01	1.0	0.16094	mg	
Substance	2	Copper	Supplier	7440-50-8	98.9875	1.0	1593.10483	mg	
Substance	2	Cobalt	Supplier	7440-48-4	0.1	1.0	1.6094	mg	
Substance	2	Arsenic	Supplier	7440-38-2	0.01	1.0	0.16094	mg	
Substance	2	Tellurium	Supplier	13494-80-9	0.7	1.0	11.2658	mg	
Substance	2	Beryllium	Supplier	7440-41-7	0.0010	1.0	0.016094	mg	
Substance	2	Phosphorus	Supplier	7723-14-0	0.01	1.0	0.16094	mg	
Substance	2	Lead	Lead/Lead Compounds	7439-92-1	0.1	1.0	1.6094	mg	
Substance	2	Nickel	Nickel	7440-02-0	0.05	1.0	0.8047	mg	
Substance	2	Cadmium	Cadmium/Cadmium Compounds	7440-43-9	0.01	1.0	0.16094	mg	
Substance	2	Mercury	Mercury/Mercury Compounds	7439-97-6	5.0E-4	1.0	0.008047	mg	
Material	1	Nickel Plate				1.0	2.982	mg	

Substance	2	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-1212	0.2	1.0	0.005964	mg	
Substance	2	Lead	Lead/Lead Compounds	7439-92-1	0.1	1.0	0.002982	mg	
Substance	2	Nickel	Nickel	7440-02-0	99.7	1.0	2.97305	mg	